

### REMARKS

This reply is being submitted together with a Notice of Appeal.

Claims 1-7 are pending for further examination.

Claims 8-18 were withdrawn from consideration as the result of a restriction requirement.

In the Office action, the claims were rejected as follows:

(1) Claims 1-4 and 6 were rejected as unpatentable over U.S. Patent Publication 2003/0164554 (Fee et al.) in view of U.S. Patent No. 6,630,729 (Huang).

(2) Claim 5 was rejected as unpatentable over the Fee et al. publication in view of the Huang patent further in view of U.S. Patent Publication 2002/0056926 (Jung et al.).

(3) Claim 7 was rejected as unpatentable over the Fee et al. publication in view of the Huang patent further in view of U.S. Patent No. 6,836,009 (Koon et al.).

In view of the following remarks, Applicant respectfully requests reconsideration and withdrawal of the rejections.

Claim 1 recites a circuit device comprising a conductive pattern; a circuit element, affixed onto the conductive pattern; and an insulating resin that seals the conductive pattern and the circuit element while exposing at least a bottom surface of the conductive pattern. The side surfaces of the insulating resin has "recessed areas" such that outwardly facing outer peripheral parts of the conductive pattern are exposed from within the recessed areas.

An example is illustrated in FIG. 1 in which a resin is identified by reference numeral 14 and includes recesses 15. Outwardly facing peripheral parts of the bonding pads 12 are exposed from within the recesses 15.

The Huang patent discloses a semiconductor package 30 that includes a semiconductor chip 31, a number of leads 33, and an encapsulant 39. As shown in FIG. 3, each lead 33 has a connecting mechanism 34 that extends from a surface 33a toward the semiconductor chip 31. Metal wires 37 electrically connect the connecting mechanisms 34 to the semiconductor chip 31.

The Office action alleges that the encapsulant 39 of the Huang patent has “recessed areas” located in its side surfaces. That is incorrect. Instead, the side surfaces of the encapsulant 39 are in the same plane as and are substantially flush with the outwardly facing surfaces of the leads 33. The area of FIG. 10E that is shaded with diagonal lines show a lead frame 332 from which the leads 33 are formed and the connecting mechanisms 34 extend. The lead frame 332 and leads 33 define “molding cavities” that are filled with the encapsulant 39 (*see* column 6, lines 16-18). FIG. 10D shows the lead frame 332 before the cavities are filled and FIG. 10E shows the lead frame afterwards. Thus, when the lead frame 332 is diced along the cutting lines 392 in the final step of the fabrication process (*see* FIG. 10G), the resulting packages 30 have side surfaces that are flat (*i.e.*, the side surfaces include both the encapsulant 39 and the leads 33 on the same planes). Therefore, the encapsulant 39 does not have “recessed areas” located in its side surfaces.

Neither the Jung et al. or the Koon et al. references disclose or suggest the features missing from the Fee et al. patent.

For at least the foregoing reasons, claim 1 should be allowed. Claims 2-7 depend from claim 1 and should be allowed for at least the same reasons.

It is believed that all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession of that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reasons for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this paper.

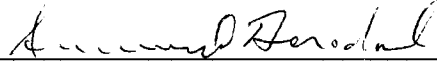
The fees for the Notice of Appeal and the Petition for Extension of Time are being paid concurrently herewith on the Electronic Filing System (EFS) by way of Deposit Account authorization. Please apply any other charges or credits to deposit account 06-1050.

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Respectfully submitted,

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